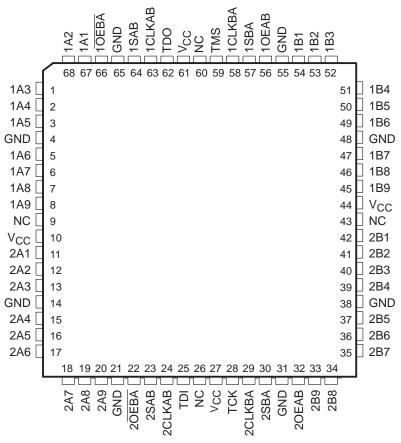
SN54ABT18652, SN74ABT18652 SCAN TEST DEVICES WITH 18-BIT BUS TRANSCEIVERS AND REGISTERS

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- Members of the Texas Instruments
 SCOPE™ Family of Testability Products
- Members of the Texas Instruments Widebus ™ Family
- Compatible With the IEEE Standard 1149.1-1990 (JTAG) Test Access Port and Boundary-Scan Architecture
- Include D-Type Flip-Flops and Control Circuitry to Provide Multiplexed Transmission of Stored and Real-Time Data
- Two Boundary-Scan Cells per I/O for Greater Flexibility
- State-of-the-Art EPIC-IIB ™ BiCMOS Design Significantly Reduces Power Dissipation

- SCOPE™ Instruction Set
 - IEEE Standard 1149.1-1990 Required Instructions, Optional INTEST, and P1149.1A CLAMP and HIGHZ
 - Parallel Signature Analysis at Inputs With Masking Option
 - Pseudo-Random Pattern Generation From Outputs
 - Sample Inputs/Toggle Outputs
 - Binary Count From Outputs
 - Device Identification
 - Even-Parity Opcodes
- Packaged in 64-Pin Plastic Shrink Quad Flat Pack (PM) and 68-Pin Ceramic Quad Flat Pack (HV)

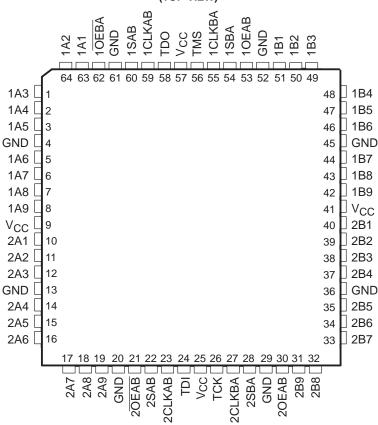
SN54ABT18652...HV PACKAGE (TOP VIEW)



NC - No internal connection



SN74ABT18652...PM PACKAGE (TOP VIEW)



description

The SN54ABT18652 and SN74ABT18652 scan test devices with 18-bit bus transceivers and registers are members of the Texas Instruments SCOPE™ testability IC family. This family of devices supports IEEE Standard 1149.1-1990 boundary scan to facilitate testing of complex circuit board assemblies. Scan access to the test circuitry is accomplished via the 4-wire test access port (TAP) interface.

In the normal mode, these devices are 18-bit bus transceivers and registers that allow for multiplexed transmission of data directly from the input bus or from the internal registers. They can be used either as two 9-bit transceivers or one 18-bit transceiver. The test circuitry can be activated by the TAP to take snapshot samples of the data appearing at the device pins or to perform a self test on the boundary test cells. Activating the TAP in the normal mode does not affect the functional operation of the SCOPE™ bus transceivers and registers.

Data flow in each direction is controlled by clock (CLKAB and CLKBA), select (SAB and SBA), and output-enable (OEAB and $\overline{\text{OEBA}}$) inputs. For A-to-B data flow, data on the A bus is clocked into the associated registers on the low-to-high transition of CLKAB. When SAB is low, real-time A data is selected for presentation to the B bus (transparent mode). When SAB is high, stored A data is selected for presentation to the B bus (registered mode). When OEAB is high, the B outputs are active. When OEAB is low, the B outputs are in the high-impedance state. Control for B-to-A data flow is similar to that for A-to-B data flow but uses CLKBA, SBA, and $\overline{\text{OEBA}}$ inputs. Since the $\overline{\text{OEBA}}$ input is active-low, the A outputs are active when $\overline{\text{OEBA}}$ is low and are in the high-impedance state when $\overline{\text{OEBA}}$ is high. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT18652.



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description (continued)

In the test mode, the normal operation of the SCOPE™ bus transceivers and registers is inhibited, and the test circuitry is enabled to observe and control the I/O boundary of the device. When enabled, the test circuitry can perform boundary scan test operations according to the protocol described in IEEE Standard 1149.1-1990.

Four dedicated test pins are used to observe and control the operation of the test circuitry: test data input (TDI), test data output (TDO), test mode select (TMS), and test clock (TCK). Additionally, the test circuitry can perform other testing functions such as parallel signature analysis on data inputs and pseudo-random pattern generation from data outputs. All testing and scan operations are synchronized to the TAP interface.

Additional flexibility is provided in the test mode through the use of two boundary scan cells (BSCs) for each I/O pin. This allows independent test data to be captured and forced at either bus (A or B). A PSA/COUNT instruction is also included to ease the testing of memories and other circuits where a binary count addressing scheme is useful.

The SN54ABT18652 is characterized over the full military temperature range of -55° C to 125°C. The SN74ABT18652 is characterized for operation from -40° C to 85°C.

FUNCTION TABLE (normal mode, each 9-bit section)

(normal mode) each of the section)											
		INPU	TS			DAT	A I/O	OPERATION OF FUNCTION			
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1 THRU A9	B1 THRU B9	OPERATION OR FUNCTION			
L	Н	L	L	Х	Х	Input disabled	Input disabled	Isolation			
L	Н	\uparrow	\uparrow	X	X	Input	Input	Store A and B data			
X	Н	\uparrow	L	X	X	Input	Unspecified [†]	Store A, hold B			
Н	Н	\uparrow	\uparrow	X‡	X	Input	Output	Store A in both registers			
L	X	L	\uparrow	X	X	Unspecified [†]	Input	Hold A, store B			
L	L	\uparrow	\uparrow	X	X‡	Output	Input	Store B in both registers			
L	L	Χ	Χ	X	L	Output	Input	Real-time B data to A bus			
L	L	Χ	L	X	Н	Output	Input	Stored B data to A bus			
Н	Н	Χ	Χ	L	X	Input	Output	Real-time A data to B bus			
Н	Н	L	Χ	Н	X	Input	Output	Stored A data to B bus			
Н	L	L	L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus			

The data output functions can be enabled or disabled by a variety of level combinations at the OEAB or OEBA inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.

Select control = H: clocks must be staggered in order to load both registers.



[‡] Select control = L: clocks can occur simultaneously.

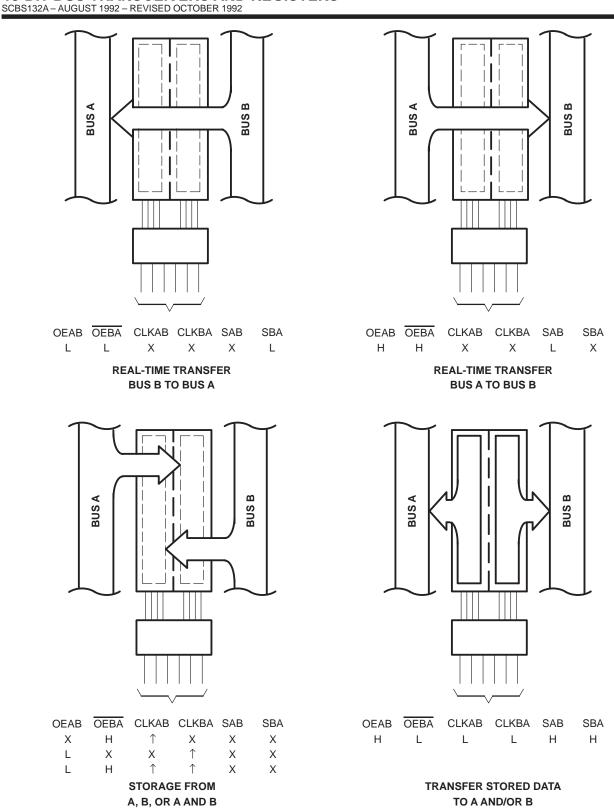
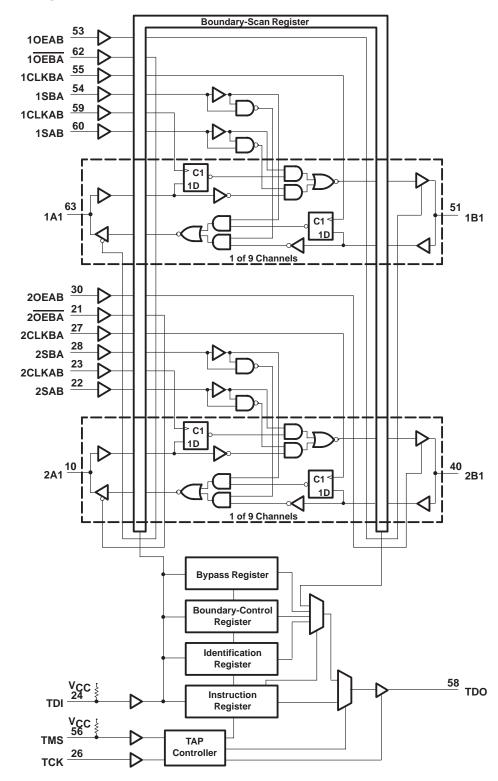


Figure 1. Bus-Management Functions



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functional block diagram



Pin numbers shown are for the PM package.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I : except I/O ports (see Note 1)	0.5 V to 7 V
I/O ports (see Note 1)	0.5 V to 5.5 V
Voltage range applied to any output in the high state or power-off state, V_{O}	0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT18652	96 mA
SN74ABT18652	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	885 mW
Storage temperature range	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. For the SN74ABT18652 (PM package), the power derating factor for ambient temperatures greater than 55°C is -10.5 mW/°C.

recommended operating conditions (see Note 3)

		SN54AB	T18652	SN74AB	UNIT	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0	Vcc	0	VCC	V
IOH	High-level output current		-24		-32	mA
loL	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Note 4)

PARAMETER	_	EST CONDITION	NIC .	Т	A = 25°C	;	SN54AE	T18652	SN74AE	T18652	UNIT	
PARAMETER	'	EST CONDITIO	ONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_1 = -18 \text{ mA}$				-1.2		-1.2		-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5			
VOH	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$		3			3		3		V	
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ m}$	A	2			2				ľ	
	VCC = 4.5 V	$I_{OH} = -32 \text{ m}$	A	2*					2			
VOL	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$				0.55		0.55			V	
VOL	VCC = 4.5 V	I _{OL} = 64 mA				0.55* ±1 ±100 10 -160				0.55	V	
lį	V _{CC} = 5.5 V, V _I = V _{CC} or GND		CLK, OEAB, OEBA, S, TCK			±1		±1		±1	μА	
	1 1 2 1 5 6 6 6 6	ND	A or B ports			±100		±100		±100		
lіН	$V_{CC} = 5.5 \text{ V},$	AI = ACC	TDI, TMS			10		10		10	μΑ	
I _{IL}	$V_{CC} = 5.5 \text{ V},$	$V_I = GND$	TDI, TMS			-160		-160		-160	μΑ	
lozh‡	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.7 \text{ V}$					50		50		50	μΑ	
lozL [‡]	$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V				-50		-50		-50	μΑ	
l _{off}	$V_{CC} = 0$,	V_I or $V_O \le 5.5$	5 V			±100		±450		±100	μΑ	
ICEX	$V_{CC} = 5.5 V$,	V _O = 5.5 V	Outputs high			50		50		50	μΑ	
IO§	$V_{CC} = 5.5 V$,	V _O = 2.5 V		-50	-100	-180	-50	-180	-50	-180	mA	
	V _C C = 5.5 V,	V _{CC} = 5.5 V,		Outputs high			4		4		4	
lcc	$I_{O} = 0$,	A or B ports	Outputs low			80		80		80	mA	
	$V_I = V_{CC}$ or GND	A of B ports	Outputs disabled			4		4		4		
ΔICC¶	V _{CC} = 5.5 V, Other inputs at		3.4 V,			1.5		1.5		1.5	mA	
Ci	V _I = 2.5 V or 0.	5 V	Control inputs		4						pF	
C _{io}	$V_0 = 2.5 \text{ V or } 0$).5 V	A or B ports		10						pF	
Co	$V_0 = 2.5 \text{ V or } 0$).5 V	TDO		8						pF	

NOTE 4: Preliminary specifications based on SPICE analysis

^{*} On products compliant to MIL-STD-883, Class B, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (normal mode) (see Note 4 and Figure 2)

		SN54AB	T18652	SN74AE	UNIT		
			MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency	CLKAB or CLKBA	0	100	0	100	MHz
t _W	Pulse duration	CLKAB or CLKBA high or low			3		ns
t _{su}	Setup time	A before CLKAB↑ or B before CLKBA↑			5		ns
t _h	Hold time	A after CLKAB↑ or B after CLKBA↑		·	0		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (test mode) (see Note 4 and Figure 2)

			SN54AI	BT18652	SN74AE		
			MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency	TCK	0	50	0	50	MHz
t _W	Pulse duration	TCK high or low			5		ns
t _{Su}		A, B, CLK, OEAB, OEBA, or S before TCK↑			5		
	Setup time	TDI before TCK↑			6		ns
		TMS before TCK↑			6		
		A, B, CLK, OEAB, OEBA, or S after TCK↑			0		
t _h	Hold time	TDI after TCK↑			0		ns
		TMS after TCK↑			0		
t _d	Delay time	Power up to TCK↑		·	50		ns
t _r	Rise time	V _{CC} power up			1		μs

NOTE 4: Preliminary specifications based on SPICE analysis



PRODUCT PREVIEW

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (normal mode) (see Note 4 and Figure 2)

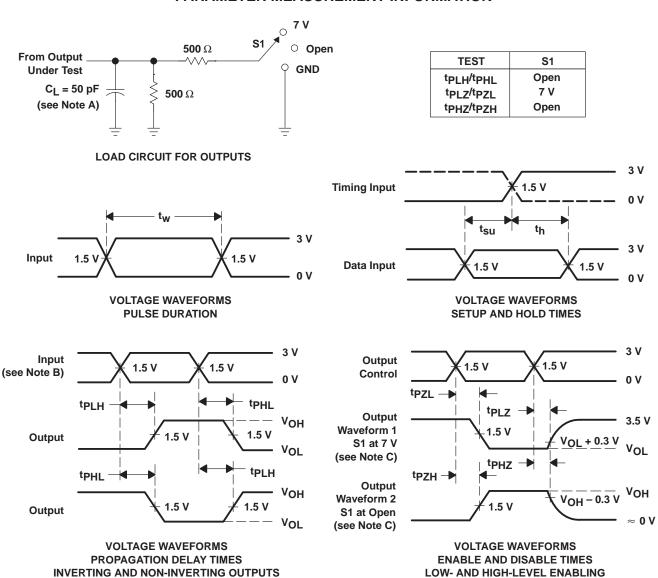
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54AE	T18652	SN74AE	UNIT		
	(INFOT)	(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
f _{max}	CLKAB or CLKBA		100	130		100		100		MHz	
^t PLH	A or B	B or A						1	6	ns	
^t PHL		BOIA						1	6] IIS	
^t PLH	CLKAB or CLKBA	B or A						2	6	ns	
^t PHL		CLNAB OF CLNBA	BOIA						2	6	113
^t PLH	SAB or SBA	SAB or SBA	B or A						2	8	ns
t _{PHL}		BOIA						2	8	113	
^t PZH	OEAB or OEBA	B or A						2	7.5		
t _{PZL}	OEAB OF OEBA	BOIA						2	7.5	ns	
^t PHZ	OEAB or OEBA	B or A						2	7.5		
tpLZ	OLAD UI OEBA	BUA						2	7.5	ns	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (test mode) (see Note 4 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54AE	3T18652	SN74AE	UNIT	
	(INPOT)	(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}	TCK		50	90		50		50		MHz
^t PLH	тск↓	A or B						3	12	ne
^t PHL	TCK↓	AUB						3	12	ns
^t PLH	TCK↓	TDO						2	7	ns
^t PHL		TDO						2	7	115
^t PZH	тск↓	A or B						3	14	ns
t _{PZL}	TCR↓							3	14	115
^t PZH	тск↓	TDO						2	8	ns
t _{PZL}	TGR∜	100						2	8	115
^t PHZ	тск↓	A or B						3	14	ns
t _{PLZ}		A or B						3	14	
^t PHZ	тск↓	TDO					·	2	8	ns
t _{PLZ}	TCK↓	100					·	2	8	115

NOTE 4: Preliminary specifications based on SPICE analysis

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns, $t_f \leq 2.5$ ns.

LOW- AND HIGH-LEVEL ENABLING

- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



PRODUCT PREVIEW

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